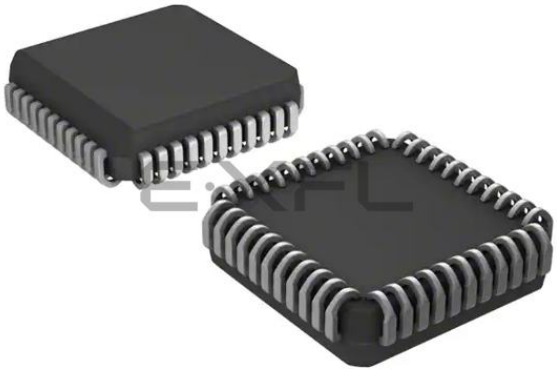

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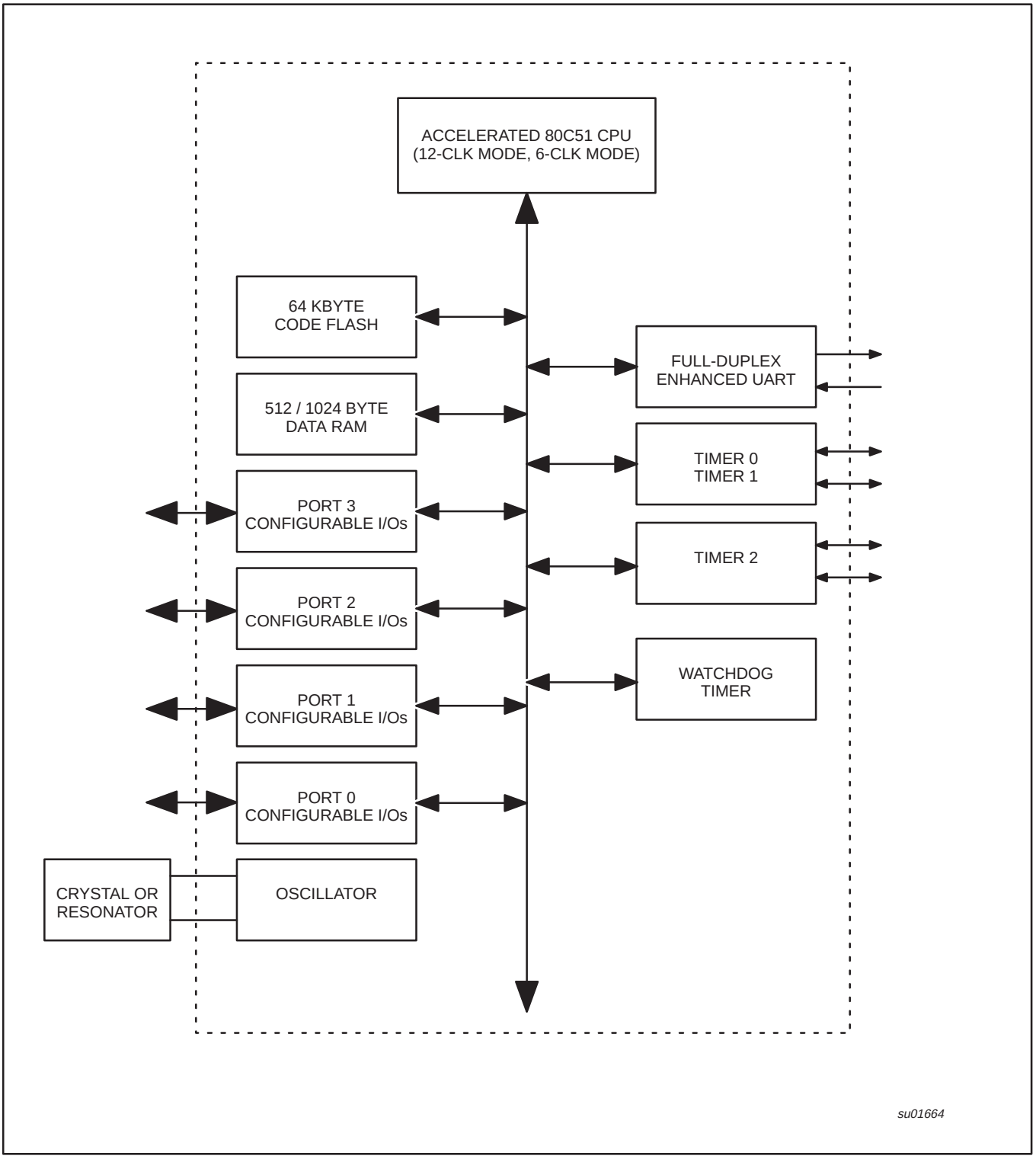
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89c61x2ba-00-512

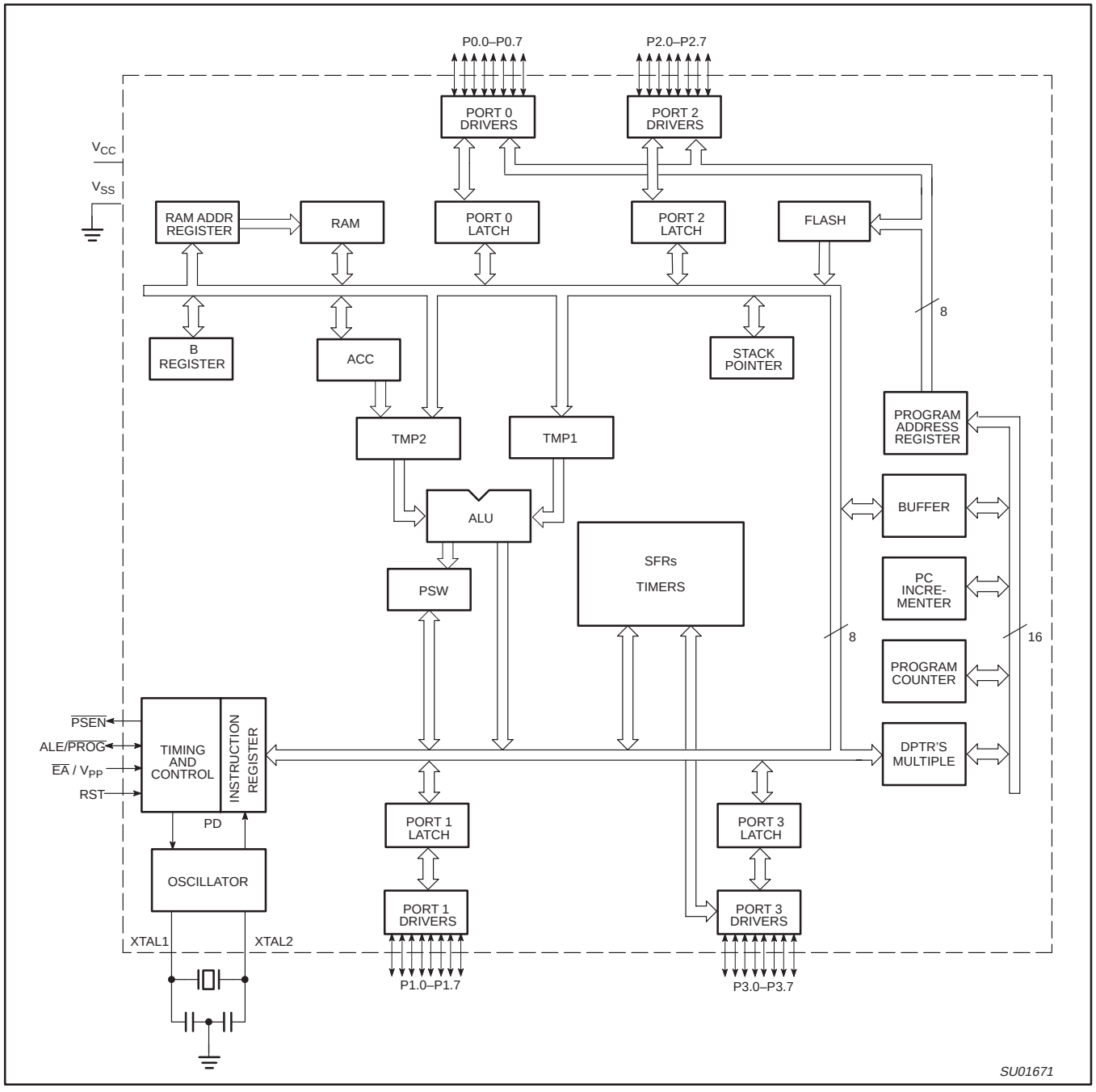
FEATURES

- 80C51 Central Processing Unit
  - 64 kbytes Flash
  - 512 bytes RAM (P89C60X2)
  - 1024 bytes RAM (P89C61X2)
  - Boolean processor
  - Fully static operation
- In-System Programmable (ISP) Flash memory
- 12-clock operation with selectable 6-clock operation (via software or via parallel programmer)
- Memory addressing capability
  - Up to 64 kbytes ROM and 64 kbytes RAM
- Power control modes:
  - Clock can be stopped and resumed
  - Idle mode
  - Power-down mode
- Two speed ranges
  - 0 to 20 MHz with 6-clock operation
  - 0 to 33 MHz with 12-clock operation
- LQFP, PLCC, and DIP packages
- Dual Data Pointers
- Three security bits
- Four interrupt priority levels
- Six interrupt sources
- Four 8-bit I/O ports
- Full-duplex enhanced UART
  - Framing error detection
  - Automatic address recognition
- Three 16-bit timers/counters T0, T1 (standard 80C51) and additional T2 (capture and compare)
- Programmable clock-out pin
- Watchdog timer
- Asynchronous port reset
- Low EMI (inhibit ALE, 6-clock mode)
- Wake-up from Power Down by an external interrupt

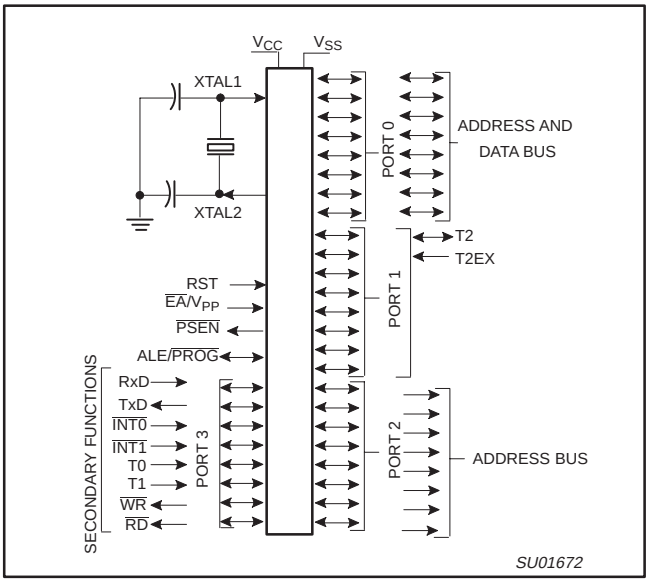
BLOCK DIAGRAM 1



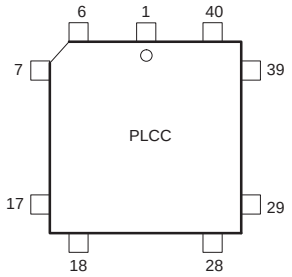
BLOCK DIAGRAM 2 (CPU-ORIENTED)



LOGIC SYMBOL



PLASTIC LEADED CHIP CARRIER PIN FUNCTIONS

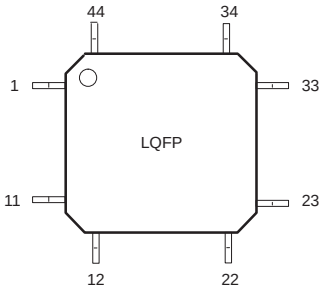


Pin	Function	Pin	Function	Pin	Function
1	NIC*	16	P3.4/T0	31	P2.7/A15
2	P1.0/T2	17	P3.5/T1	32	$\overline{PSEN}$
3	P1.1/T2EX	18	P3.6/$\overline{WR}$	33	ALE
4	P1.2	19	P3.7/$\overline{RD}$	34	NIC*
5	P1.3	20	XTAL2	35	$\overline{EA}$/V_{PP}
6	P1.4	21	XTAL1	36	P0.7/AD7
7	P1.5	22	V_{SS}	37	P0.6/AD6
8	P1.6	23	NIC*	38	P0.5/AD5
9	P1.7	24	P2.0/A8	39	P0.4/AD4
10	RST	25	P2.1/A9	40	P0.3/AD3
11	P3.0/RxD	26	P2.2/A10	41	P0.2/AD2
12	NIC*	27	P2.3/A11	42	P0.1/AD1
13	P3.1/TxD	28	P2.4/A12	43	P0.0/AD0
14	P3.2/$\overline{INT0}$	29	P2.5/A13	44	V_{CC}
15	P3.3/$\overline{INT1}$	30	P2.6/A14		

* NO INTERNAL CONNECTION

SU01062

LOW PROFILE QUAD FLAT PACK PIN FUNCTIONS

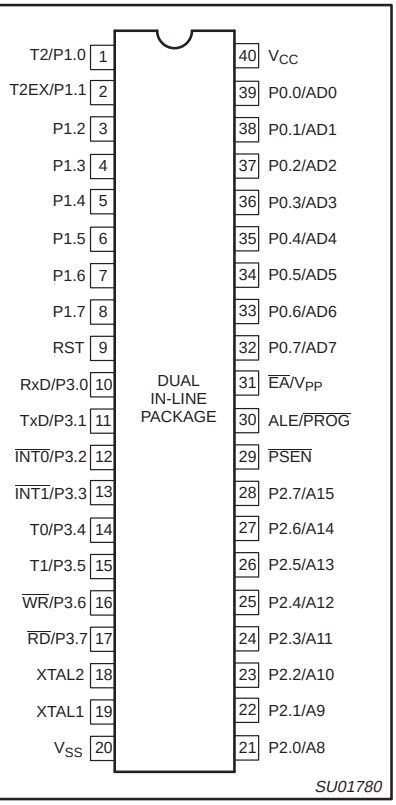


Pin	Function	Pin	Function	Pin	Function
1	P1.5	16	V_{SS}	31	P0.6/AD6
2	P1.6	17	NIC*	32	P0.5/AD5
3	P1.7	18	P2.0/A8	33	P0.4/AD4
4	RST	19	P2.1/A9	34	P0.3/AD3
5	P3.0/RxD	20	P2.2/A10	35	P0.2/AD2
6	NIC*	21	P2.3/A11	36	P0.1/AD1
7	P3.1/TxD	22	P2.4/A12	37	P0.0/AD0
8	P3.2/$\overline{INT0}$	23	P2.5/A13	38	V_{CC}
9	P3.3/$\overline{INT1}$	24	P2.6/A14	39	NIC*
10	P3.4/T0	25	P2.7/A15	40	P1.0/T2
11	P3.5/T1	26	$\overline{PSEN}$	41	P1.1/T2EX
12	P3.6/$\overline{WR}$	27	ALE	42	P1.2
13	P3.7/$\overline{RD}$	28	NIC*	43	P1.3
14	XTAL2	29	$\overline{EA}$/V_{PP}	44	P1.4
15	XTAL1	30	P0.7/AD7		

* NO INTERNAL CONNECTION

SU01487

PLASTIC DUAL IN-LINE PACKAGE PIN FUNCTIONS



NOTES:
Special Function Registers (SFRs) accesses are restricted in the following ways:
1. Do not attempt to access any SFR locations not defined.
2. Accesses to any defined SFR locations must be strictly for the functions for the SFRs.
3. SFR bits labeled '–', '0' or '1' can ONLY be written and read as follows:
   '–' MUST be written with '0', but can return any value when read (even if it was written with '0'). It is a reserved bit and may be used in future derivatives.
   '0' MUST be written with '0', and will return a '0' when read.
   '1' MUST be written with '1', and will return a '1' when read.

*: SFRs are bit addressable.
#: SFRs are modified from or added to the 80C51 SFRs.
–: Reserved bits (see note above).
1: Reset value depends on reset source.

TCON Address = 88H Reset Value = 00H

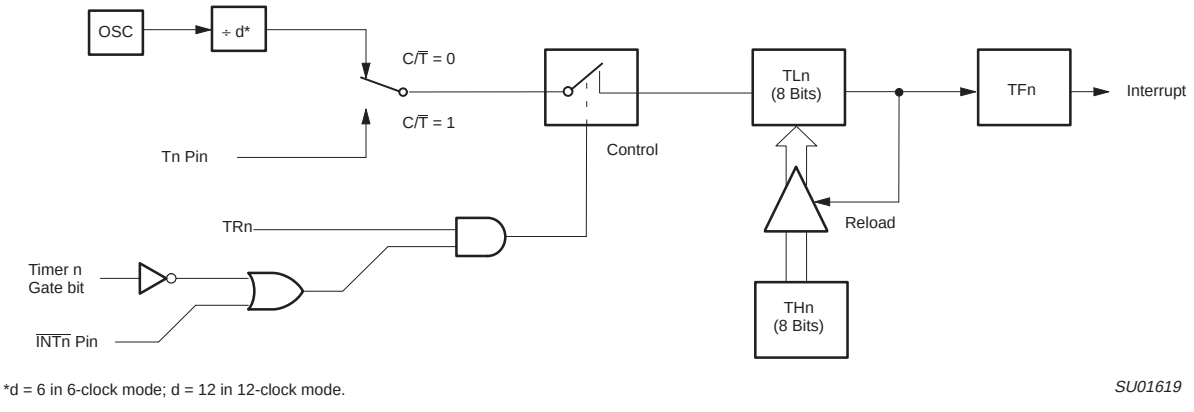
Bit Addressable

7	6	5	4	3	2	1	0
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0

BIT	SYMBOL	FUNCTION
TCON.7	TF1	Timer 1 overflow flag. Set by hardware on Timer/Counter overflow. Cleared by hardware when processor vectors to interrupt routine, or clearing the bit in software.
TCON.6	TR1	Timer 1 Run control bit. Set/cleared by software to turn Timer/Counter on/off.
TCON.5	TF0	Timer 0 overflow flag. Set by hardware on Timer/Counter overflow. Cleared by hardware when processor vectors to interrupt routine, or by clearing the bit in software.
TCON.4	TR0	Timer 0 Run control bit. Set/cleared by software to turn Timer/Counter on/off.
TCON.3	IE1	Interrupt 1 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TCON.2	IT1	Interrupt 1 type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.
TCON.1	IE0	Interrupt 0 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TCON.0	IT0	Interrupt 0 Type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.

SU01516

Figure 5. Timer/Counter 0/1 Control (TCON) Register



*d = 6 in 6-clock mode; d = 12 in 12-clock mode.

SU01619

Figure 6. Timer/Counter 0/1 Mode 2: 8-Bit Auto-Reload

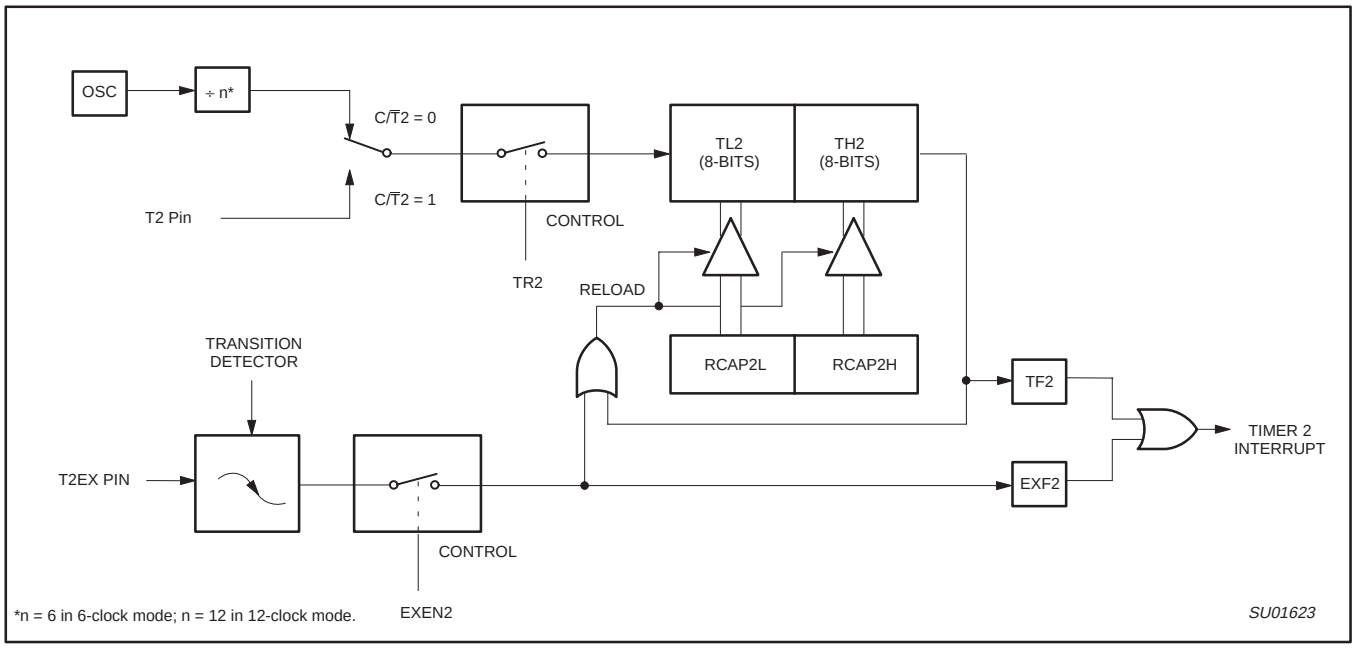


Figure 11. Timer 2 in Auto-Reload Mode (DCEN = 0)

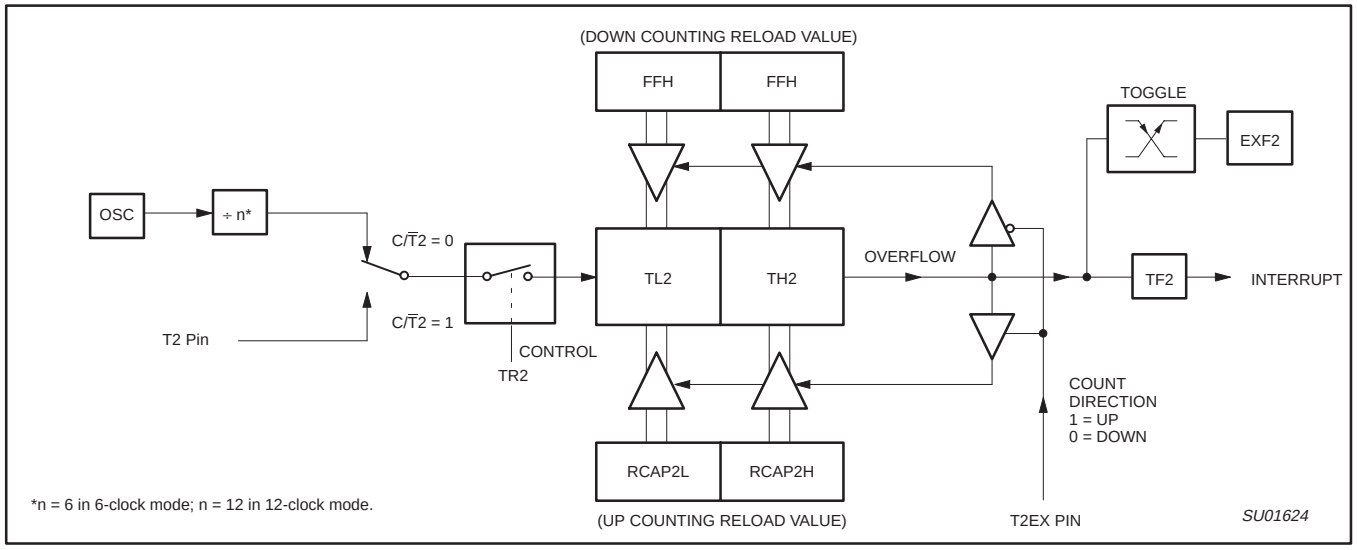


Figure 12. Timer 2 Auto Reload Mode (DCEN = 1)

SCON Address = 98H Reset Value = 00H
Bit Addressable

7	6	5	4	3	2	1	0
SM0	SM1	SM2	REN	TB8	RB8	TI	RI

Where SM0, SM1 specify the serial port mode, as follows:

SM0	SM1	Mode	Description	Baud Rate
0	0	0	shift register	$f_{OSC}/12$ (12-clock mode) or $f_{OSC}/6$ (6-clock mode)
0	1	1	8-bit UART	variable
1	0	2	9-bit UART	$f_{OSC}/64$ or $f_{OSC}/32$ (12-clock mode) or $f_{OSC}/32$ or $f_{OSC}/16$ (6-clock mode)
1	1	3	9-bit UART	variable

SM2 Enables the multiprocessor communication feature in Modes 2 and 3. In Mode 2 or 3, if SM2 is set to 1, then RI will not be activated if the received 9th data bit (RB8) is 0. In Mode 1, if SM2=1 then RI will not be activated if a valid stop bit was not received. In Mode 0, SM2 should be 0.

REN Enables serial reception. Set by software to enable reception. Clear by software to disable reception.

TB8 The 9th data bit that will be transmitted in Modes 2 and 3. Set or clear by software as desired.

RB8 In Modes 2 and 3, is the 9th data bit that was received. In Mode 1, it SM2=0, RB8 is the stop bit that was received. In Mode 0, RB8 is not used.

TI Transmit interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission. Must be cleared by software.

RI Receive interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or halfway through the stop bit time in the other modes, in any serial reception (except see SM2). Must be cleared by software.

SU01626

Figure 14. Serial Port Control (SCON) Register

Baud Rate			f_{OSC}	SMOD	Timer 1		
Mode	12-clock mode	6-clock mode			C/$\overline{T}$	Mode	Reload Value
Mode 0 Max	1.67 MHz	3.34 MHz	20 MHz	X	X	X	X
Mode 2 Max	625 k	1250 k	20 MHz	1	X	X	X
Mode 1, 3 Max	104.2 k	208.4 k	20 MHz	1	0	2	FFH
Mode 1, 3	19.2 k	38.4 k	11.059 MHz	1	0	2	FDH
	9.6 k	19.2 k	11.059 MHz	0	0	2	FDH
	4.8 k	9.6 k	11.059 MHz	0	0	2	FAH
	2.4 k	4.8 k	11.059 MHz	0	0	2	F4H
	1.2 k	2.4 k	11.059 MHz	0	0	2	E8H
	137.5	275	11.986 MHz	0	0	2	1DH
	110	220	6 MHz	0	0	2	72H
	110	220	12 MHz	0	0	1	FEEBH

Figure 15. Timer 1 Generated Commonly Used Baud Rates

More About Mode 0

Serial data enters and exits through RxD. TxD outputs the shift clock. 8 bits are transmitted/received: 8 data bits (LSB first). The baud rate is fixed at 1/12 the oscillator frequency (12-clock mode) or 1/6 the oscillator frequency (6-clock mode).

Figure 16 shows a simplified functional diagram of the serial port in Mode 0, and associated timing.

Transmission is initiated by any instruction that uses SBUF as a destination register. The “write to SBUF” signal at S6P2 also loads a 1 into the 9th position of the transmit shift register and tells the TX Control block to commence a transmission. The internal timing is such that one full machine cycle will elapse between “write to SBUF” and activation of SEND.

SEND enables the output of the shift register to the alternate output function line of P3.0 and also enable SHIFT CLOCK to the alternate output function line of P3.1. SHIFT CLOCK is low during S3, S4, and S5 of every machine cycle, and high during S6, S1, and S2. At S6P2 of every machine cycle in which SEND is active, the contents of the transmit shift are shifted to the right one position.

As data bits shift out to the right, zeros come in from the left. When the MSB of the data byte is at the output position of the shift register, then the 1 that was initially loaded into the 9th position, is just to the left of the MSB, and all positions to the left of that contain zeros. This condition flags the TX Control block to do one last shift and then deactivate SEND and set T1. Both of these actions occur at S1P1 of the 10th machine cycle after “write to SBUF.”

Reception is initiated by the condition REN = 1 and R1 = 0. At S6P2 of the next machine cycle, the RX Control unit writes the bits 11111110 to the receive shift register, and in the next clock phase activates RECEIVE.

RECEIVE enable SHIFT CLOCK to the alternate output function line of P3.1. SHIFT CLOCK makes transitions at S3P1 and S6P1 of every machine cycle. At S6P2 of every machine cycle in which RECEIVE is active, the contents of the receive shift register are

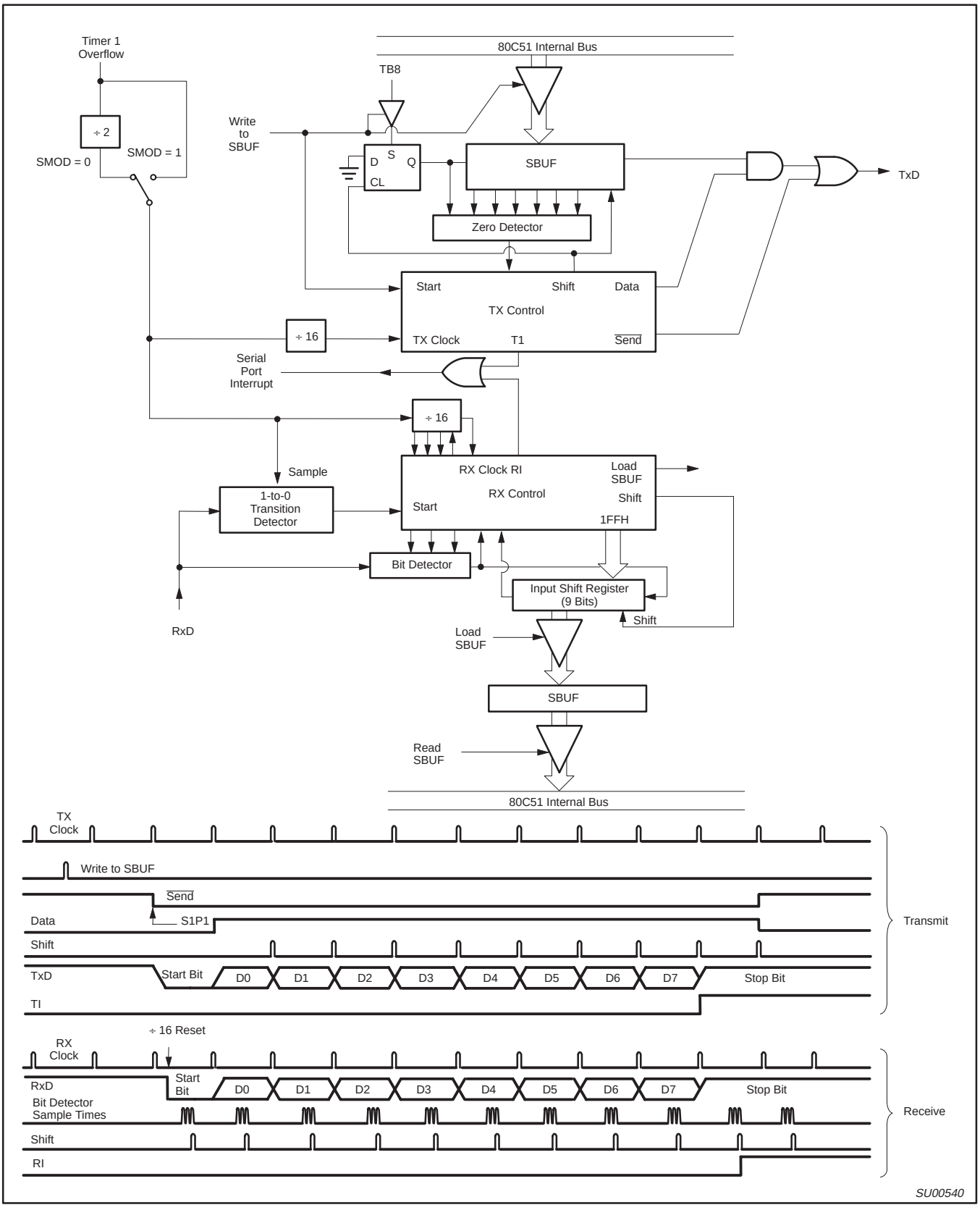


Figure 17. Serial Port Mode 1

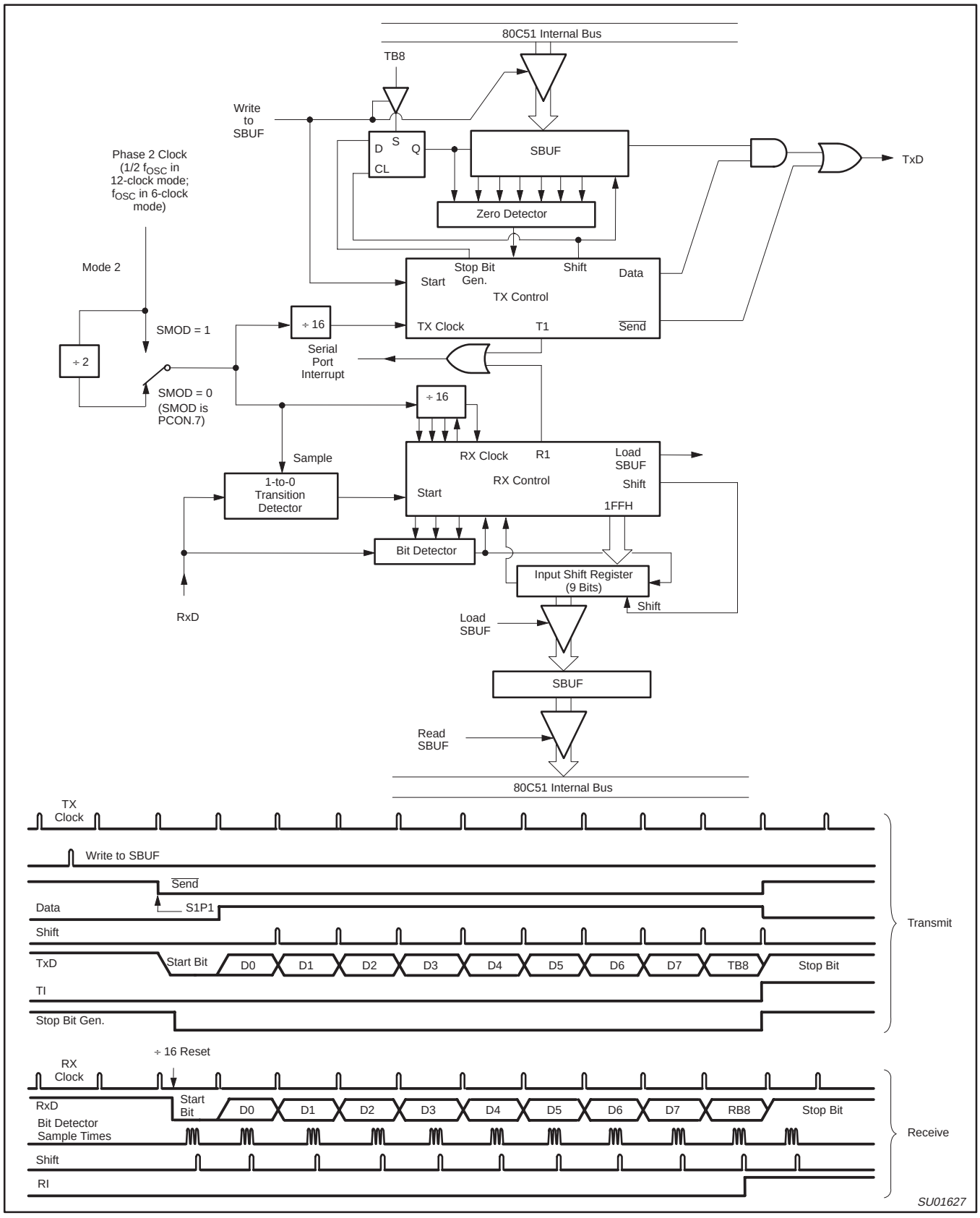


Figure 18. Serial Port Mode 2

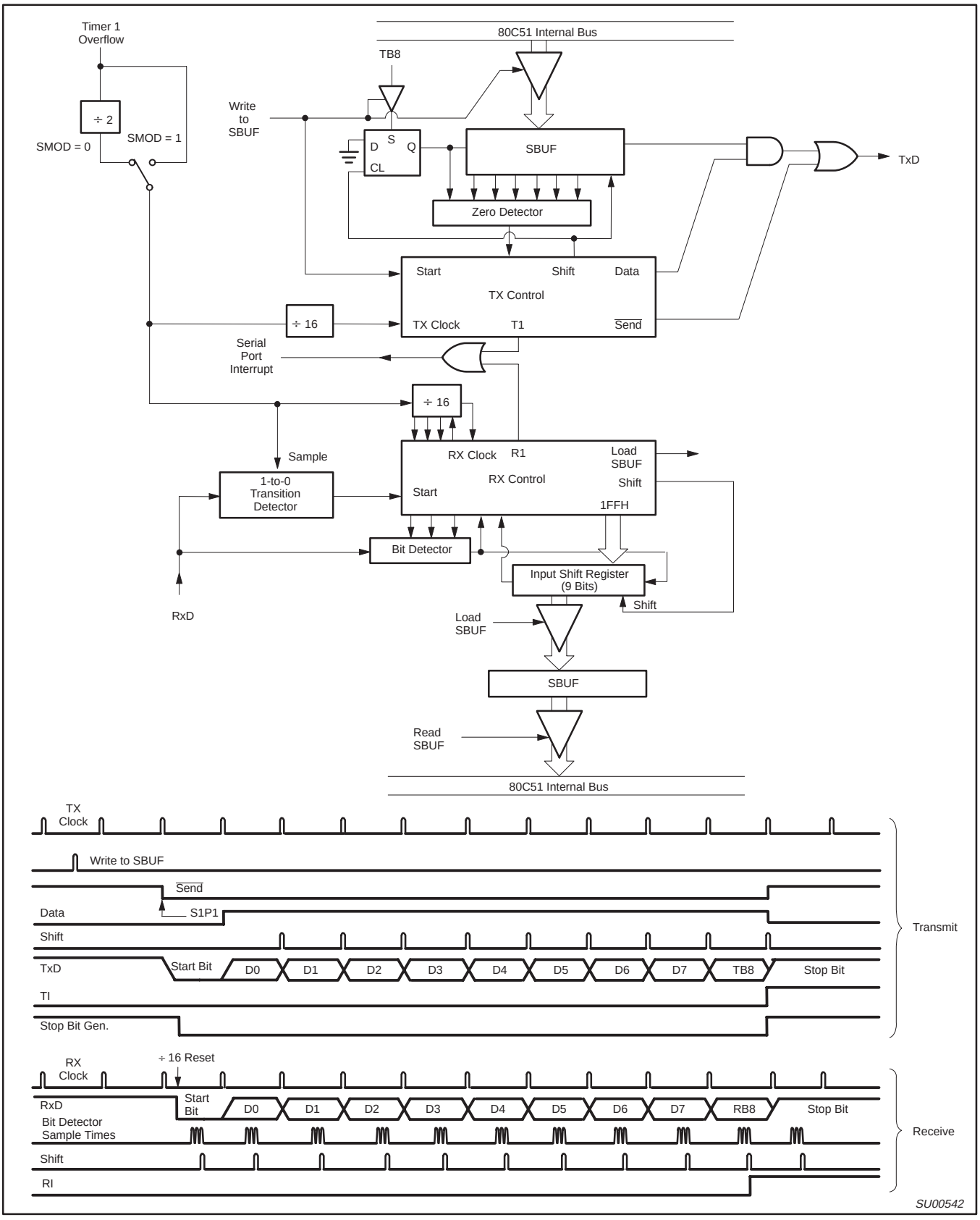


Figure 19. Serial Port Mode 3

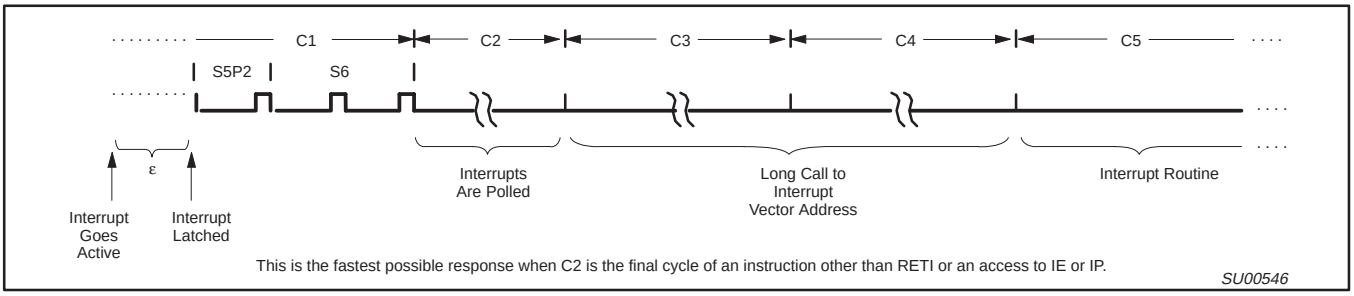


Figure 27. Interrupt Response Timing Diagram

The polling cycle/LCALL sequence is illustrated in Figure 27.

Note that if an interrupt of higher priority level goes active prior to S5P2 of the machine cycle labeled C3 in Figure 27, then in accordance with the above rules it will be vectored to during C5 and C6, without any instruction of the lower priority routine having been executed.

Thus the processor acknowledges an interrupt request by executing a hardware-generated LCALL to the appropriate servicing routine. In some cases it also clears the flag that generated the interrupt, and in other cases it doesn't. It never clears the Serial Port flag. This has to be done in the user's software. It clears an external interrupt flag (IE0 or IE1) only if it was transition-activated. The hardware-generated LCALL pushes the contents of the Program Counter on to the stack (but it does not save the PSW) and reloads the PC with an address that depends on the source of the interrupt being vectored to, as shown in Table 10.

Execution proceeds from that location until the RETI instruction is encountered. The RETI instruction informs the processor that this interrupt routine is no longer in progress, then pops the top two bytes from the stack and reloads the Program Counter. Execution of the interrupted program continues from where it left off.

Note that a simple RET instruction would also have returned execution to the interrupted program, but it would have left the interrupt control system thinking an interrupt was still in progress, making future interrupts impossible.

External Interrupts

The external sources can be programmed to be level-activated or transition-activated by setting or clearing bit IT1 or IT0 in Register TCON. If ITx = 0, external interrupt x is triggered by a detected low at the $\overline{\text{INT}}$x pin. If ITx = 1, external interrupt x is edge triggered. In this mode if successive samples of the $\overline{\text{INT}}$x pin show a high in one cycle and a low in the next cycle, interrupt request flag IEx in TCON is set. Flag bit IEx then requests the interrupt.

Since the external interrupt pins are sampled once each machine cycle, an input high or low should hold for at least 12 oscillator periods to ensure sampling. If the external interrupt is transition-activated, the external source has to hold the request pin high for at least one cycle, and then hold it low for at least one cycle. This is done to ensure that the transition is seen so that interrupt request flag IEx will be set. IEx will be automatically cleared by the CPU when the service routine is called.

If the external interrupt is level-activated, the external source has to hold the request active until the requested interrupt is actually generated. Then it has to deactivate the request before the interrupt service routine is completed, or else another interrupt will be generated.

Response Time

The $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ levels are inverted and latched into IE0 and IE1 at S5P2 of every machine cycle. The values are not actually polled by the circuitry until the next machine cycle. If a request is active and conditions are right for it to be acknowledged, a hardware subroutine call to the requested service routine will be the next instruction to be executed. The call itself takes two cycles. Thus, a minimum of three complete machine cycles elapse between activation of an external interrupt request and the beginning of execution of the first instruction of the service routine. Figure 27 shows interrupt response timings.

A longer response time would result if the request is blocked by one of the 3 previously listed conditions. If an interrupt of equal or higher priority level is already in progress, the additional wait time obviously depends on the nature of the other interrupt's service routine. If the instruction in progress is not in its final cycle, the additional wait time cannot be more the 3 cycles, since the longest instructions (MUL and DIV) are only 4 cycles long, and if the instruction in progress is RETI or an access to IE or IP, the additional wait time cannot be more than 5 cycles (a maximum of one more cycle to complete the instruction in progress, plus 4 cycles to complete the next instruction if the instruction is MUL or DIV).

Thus, in a single-interrupt system, the response time is always more than 3 cycles and less than 9 cycles.

As previously mentioned, the derivatives described in this data sheet have a four-level interrupt structure. The corresponding registers are IE, IP and IPH. (See Figures 24, 25, and 26.) The IPH (Interrupt Priority High) register makes the four-level interrupt structure possible.

The function of the IPH SFR is simple and when combined with the IP SFR determines the priority of each interrupt. The priority of each interrupt is determined as shown in the following table:

PRIORITY BITS		INTERRUPT PRIORITY LEVEL
IPH.x	IP.x	
0	0	Level 0 (lowest priority)
0	1	Level 1
1	0	Level 2
1	1	Level 3 (highest priority)

An interrupt will be serviced as long as an interrupt of equal or higher priority is not already being serviced. If an interrupt of equal or higher level priority is being serviced, the new interrupt will wait until it is finished before being serviced. If a lower priority level interrupt is being serviced, it will be stopped and the new interrupt serviced. When the new interrupt is finished, the lower priority level interrupt that was stopped will be completed.

Table 10. Interrupt Table

SOURCE	POLLING PRIORITY	REQUEST BITS	HARDWARE CLEAR?	VECTOR ADDRESS
External interrupt 0	1	IE0	N (L)[1] Y (T)[2]	03H
Timer 0	2	TF0	Y	0BH
External interrupt 1	3	IE1	N (L) Y (T)	13H
Timer 1	4	TF1	Y	1BH
UART	5	RI, TI	N	23H
Timer 2	6	TF2, EXF2	N	2BH

NOTES:
1. L = Level activated
2. T = Transition activated

Reduced EMI Mode

The AO bit (AUXR.0) in the AUXR register when set disables the ALE output, unless the CPU needs to perform an off-chip memory access.

AUXR (8EH)

7	6	5	4	3	2	1	0
–	–	–	–	–	–	EXTRAM	AO

AUXR.0	AO	Turns off ALE output.
AUXR.1	EXTRAM	Controls external data memory access.

Dual DPTR

The dual DPTR structure (see Figure 28) enables a way to specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 that allows the program code to switch between them.

- New Register Name: AUXR1#
- SFR Address: A2H
- Reset Value: xxx000x0B

AUXR1 (A2H)

7	6	5	4	3	2	1	0
–	–	–	–	GF2	0	–	DPS

Where:
DPS = AUXR1/bit0 = Switches between DPTR0 and DPTR1.

Select Reg	DPS
DPTR0	0
DPTR1	1

The DPS bit status should be saved by software when switching between DPTR0 and DPTR1.

The GF2 bit is a general purpose user-defined flag.

Note that bit 2 is not writable and is always read as a zero. This allows the DPS bit to be quickly toggled simply by executing an INC AUXR1 instruction without affecting the GF2 bit.

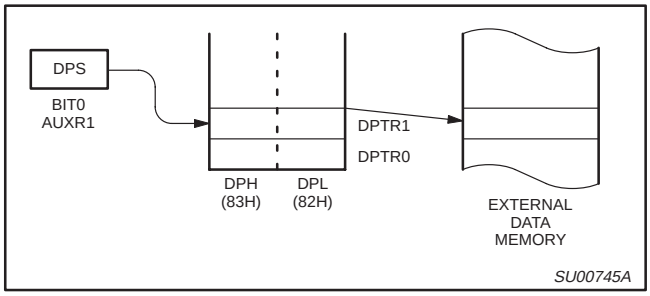


Figure 28.

DPTR Instructions

The instructions that refer to DPTR refer to the data pointer that is currently selected using the AUXR1/bit 0 register. The six instructions that use the DPTR are as follows:

INC DPTR	Increments the data pointer by 1
MOV DPTR, #data16	Loads the DPTR with a 16-bit constant
MOV A, @ A+DPTR	Move code byte relative to DPTR to ACC
MOVX A, @ DPTR	Move external RAM (16-bit address) to ACC
MOVX @ DPTR , A	Move ACC to external RAM (16-bit address)
JMP @ A + DPTR	Jump indirect relative to DPTR

The data pointer can be accessed on a byte-by-byte basis by specifying the low or high byte in an instruction which accesses the SFRs. See application note AN458 for more details.

Expanded Data RAM Addressing

The P89C60X2 has internal data memory that is mapped into four separate segments: the lower 128 bytes of RAM, upper 128 bytes of RAM, 128 bytes Special Function Register (SFR), and 256 bytes expanded RAM (ERAM) (768 bytes for the P89C61X2).

The four segments are:

1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
4. The 256/768-bytes expanded RAM (ERAM, 00H – 1FFH/2FFH) are indirectly accessed by move external instruction, MOVX, and with the EXTRAM bit cleared, see Figure 29.

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction. Instructions that use direct addressing access SFR space. For example:

MOV 0A0H,#data

accesses the SFR at location 0A0H (which is P2). Instructions that use indirect addressing access the Upper 128 bytes of data RAM.

For example:

MOV @R0,acc

where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

The ERAM can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory is physically located on-chip, logically occupies the first 256/768 bytes of external data memory in the P89C60X2/61X2.

With EXTRAM = 0, the ERAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. An access to ERAM will not affect ports P0, P3.6 (WR#) and P3.7 (RD#). P2 SFR is output during external addressing. For example, with EXTRAM = 0,

MOVX @R0,acc

where R0 contains 0A0H, accesses the ERAM at address 0A0H rather than external memory. An access to external data memory locations higher than the ERAM will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address bus, and P3.6 and P3.7 as write and read timing signals. Refer to Figure 30.

With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an 8-bit address multiplexed with data on Port 0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a 16-bit address. Port 2 outputs the high-order eight address bits (the contents of DPH) while Port 0 multiplexes the low-order eight address bits (DPL) with data. MOVX @Ri and MOVX @DPTR will generate either read or write signals on P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the ERAM.

AUXR Address = 8EH — Reset Value = xxxx xx00B

Not Bit Addressable

	—	—	—	—	—	—	**EXTRAM**	**AO**
Bit:	7	6	5	4	3	2	1	0

Symbol	Function
AO	Disable/Enable ALE
	AO **Operating Mode** 0 ALE is emitted at a constant rate of $^1/_6$ the oscillator frequency (12-clock mode; $^1/_3$ f_{OSC} in 6-clock mode). 1 ALE is active only during off-chip memory access.
EXTRAM	Internal/External RAM access using MOVX @Ri/@DPTR
	EXTRAM **Operating Mode** 0 Internal ERAM access using MOVX @Ri/@DPTR 1 External data memory access.
—	Not implemented, reserved for future use*.

NOTE:
*User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU01613

Figure 29. AUXR: Auxiliary Register

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0 °C to +70 °C; V_{CC} = 5 V ±10%; V_{SS} = 0 V (20/33 MHz max. CPU clock)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage[11]	4.5 V < V_{CC} < 5.5 V	–0.5		0.2 V_{CC}–0.1	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)	–	0.2 V_{CC}+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST[11]	–	0.7 V_{CC}		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, 3 [8]	V_{CC} = 4.5 V; I_{OL} = 1.6 mA[2]	–		0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$ [7, 8]	V_{CC} = 4.5 V; I_{OL} = 3.2 mA[2]	–		0.45	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 4.5 V; I_{OH} = –30 µA	V_{CC} – 0.7		–	V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 4.5 V; I_{OH} = –3.2 mA	V_{CC} – 0.7		–	V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4 V	–1		–75	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0 V; See note 4	–		–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3	–		±10	µA
I_{CC}	Power supply current (see Figure 38):	See note 5				
	Active mode (see Note 5)					
	Idle mode (see Note 5)					
	Power-down mode or clock stopped	T_{amb} = 0 °C to 70 °C		<30	100	µA
	(see Figure 42 for conditions)					
	Programming and erase mode	f_{OSC} = 20MHz		60		mA
R_{RST}	Internal reset pull-down resistor	–	40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)	–	–		15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5 V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE pin may exceed 0.8 V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5 mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the V_{CC}–0.7 specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2 V.
5. See Figures 39 through 42 for I_{CC} test conditions and Figure 38 for I_{CC} vs. Frequency.
   12-clock mode characteristics:
   Active mode: I_{CC} (MAX) = (8.5 + 0.62 × FREQ. [MHz])mA
   Idle mode: I_{CC} (MAX) = (3.5 + 0.18 × FREQ. [MHz])mA
6. This value applies to T_{amb} = 0°C to +70°C.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15 mA
   Maximum I_{OL} per 8-bit port: 26 mA
   Maximum total I_{OL} for all outputs: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25 pF. Pin capacitance of ceramic package is less than 15 pF (except $\overline{EA}$ is 25 pF).
11. To improve noise rejection a nominal 100 ns glitch rejection circuitry has been added to the RST pin, and a nominal 15 ns glitch rejection circuitry has been added to the $\overline{INT0}$ and $\overline{INT1}$ pins. Previous devices provided only an inherent 5 ns of glitch rejection.

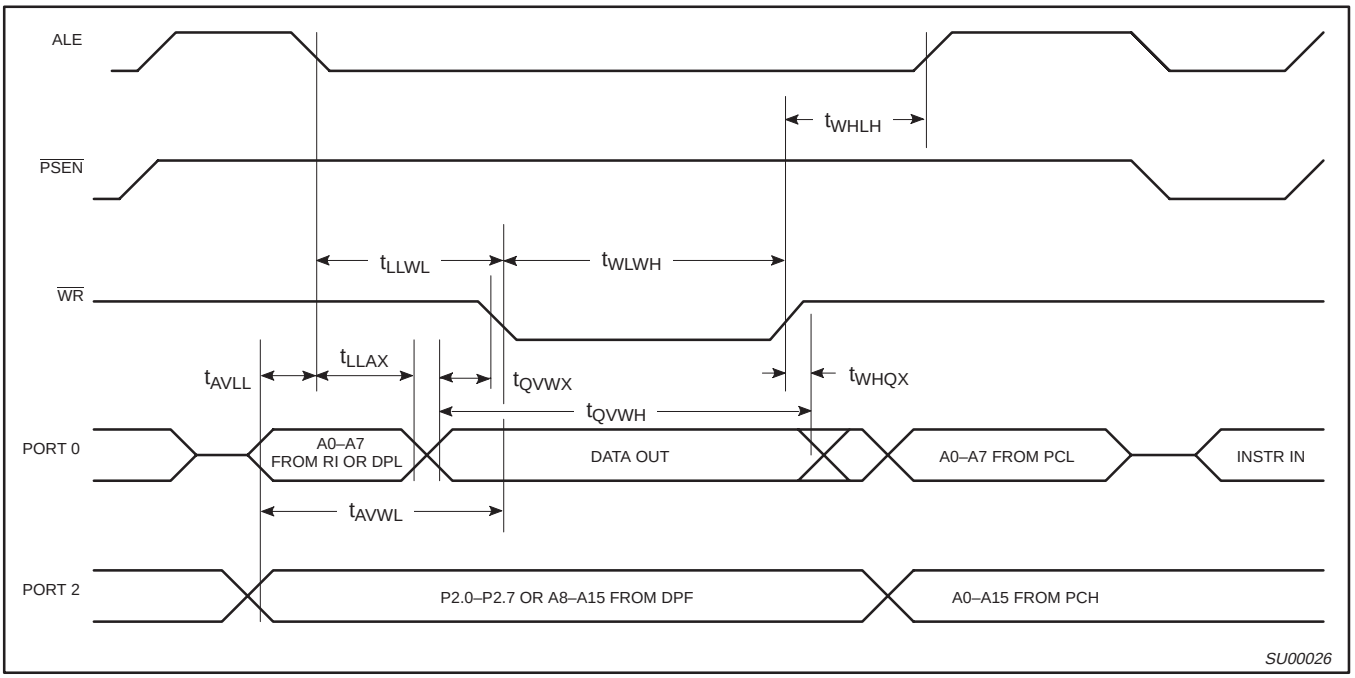


Figure 33. External Data Memory Write Cycle

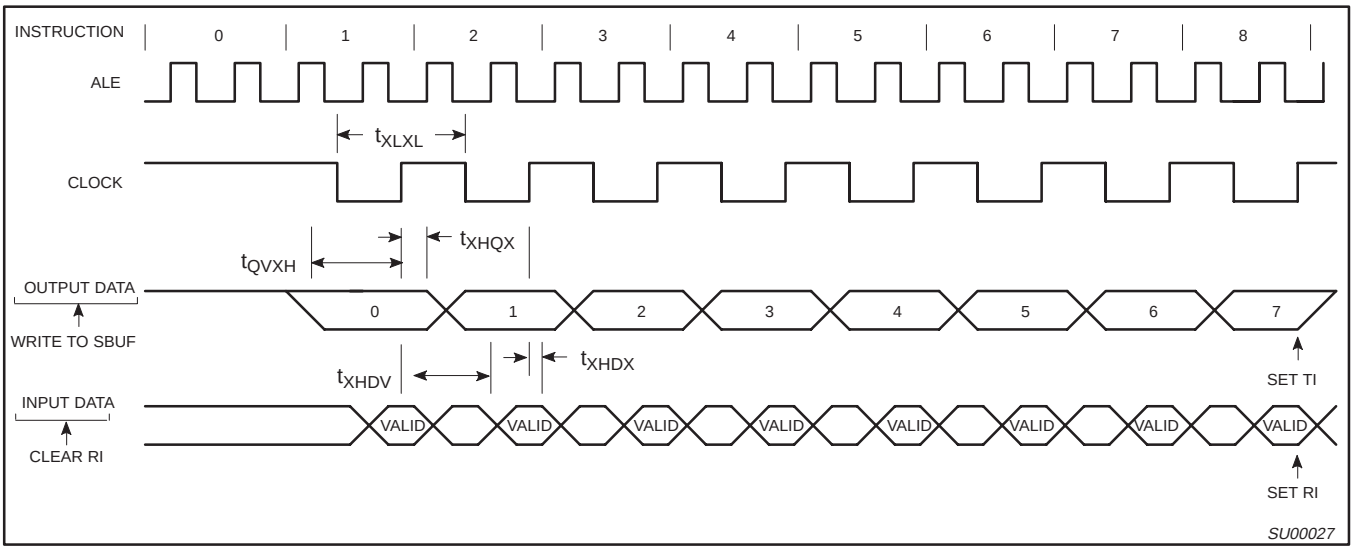


Figure 34. Shift Register Mode Timing

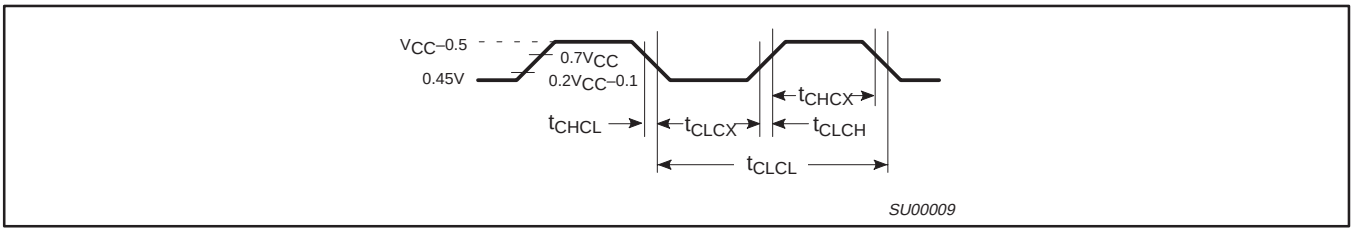


Figure 35. External Clock Drive

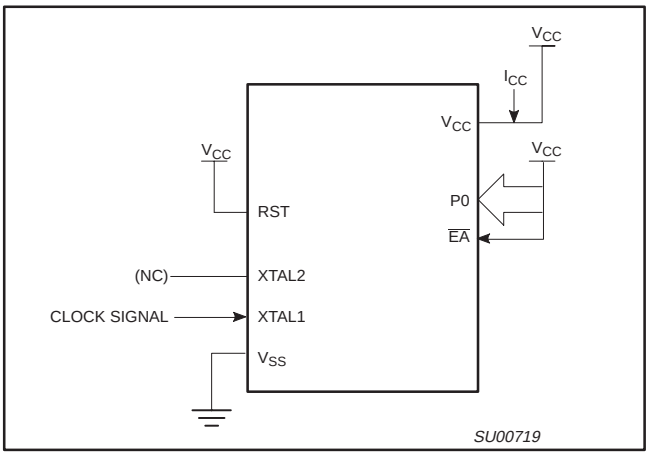


Figure 39. I_{CC} Test Condition, Active Mode
All other pins are disconnected

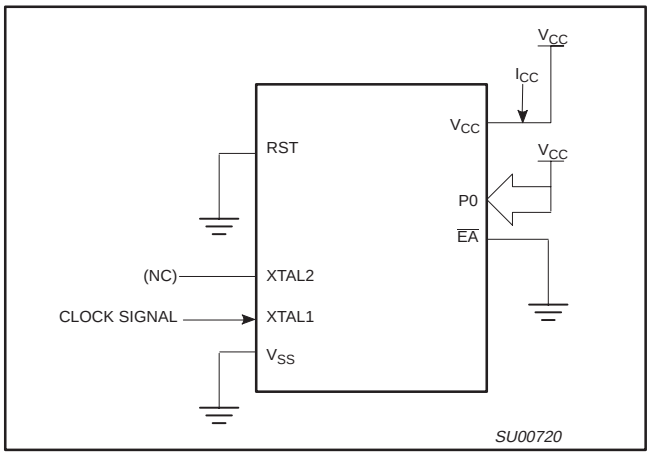


Figure 40. I_{CC} Test Condition, Idle Mode
All other pins are disconnected

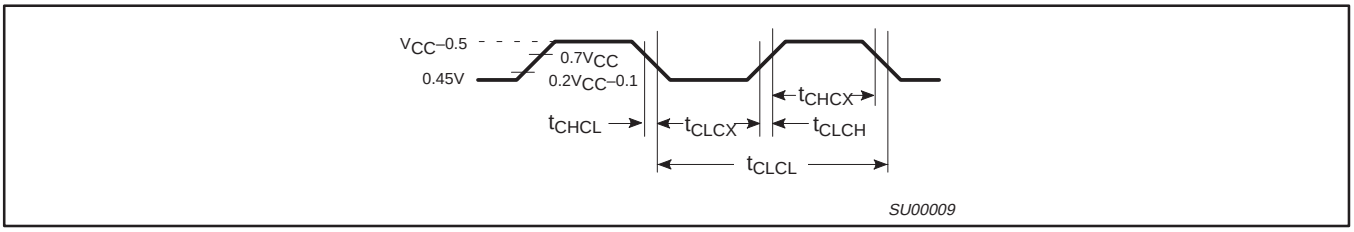


Figure 41. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes
$t_{CLCH} = t_{CHCL} = 5ns$

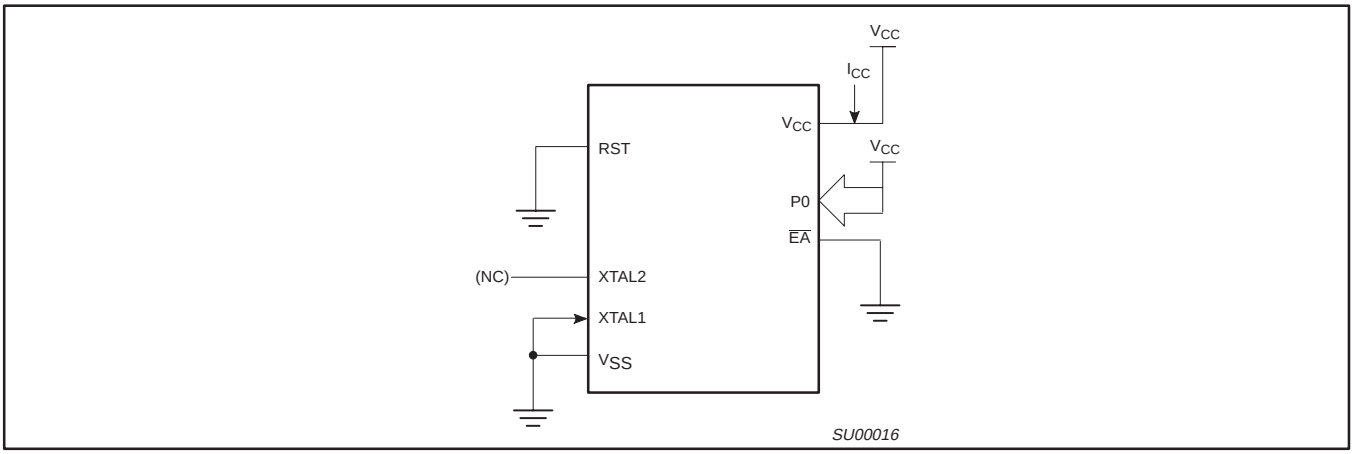
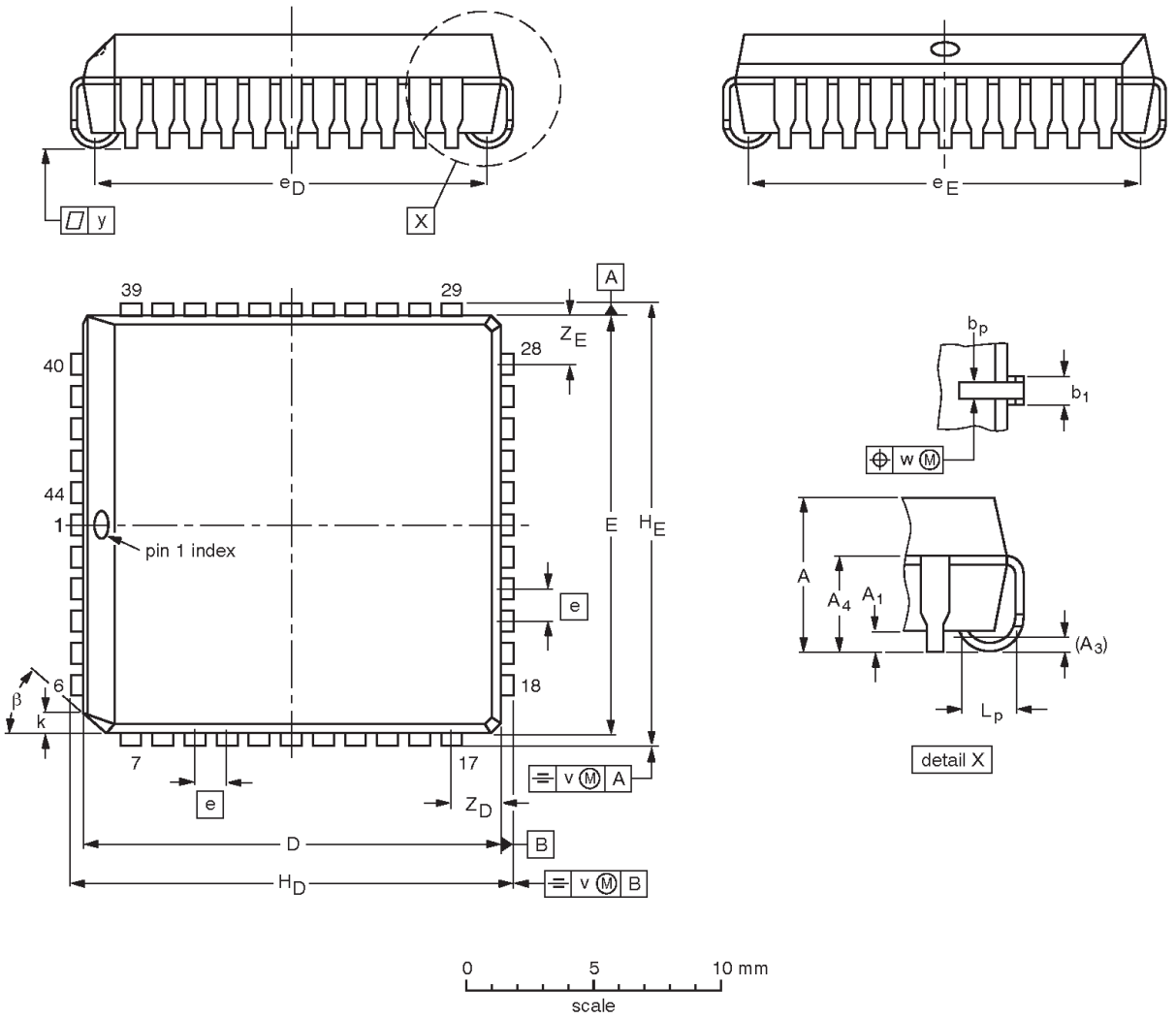


Figure 42. I_{CC} Test Condition, Power Down Mode
All other pins are disconnected. V_{CC} = 2 V to 5.5 V

PLCC44: plastic leaded chip carrier; 44 leads SOT187-2



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

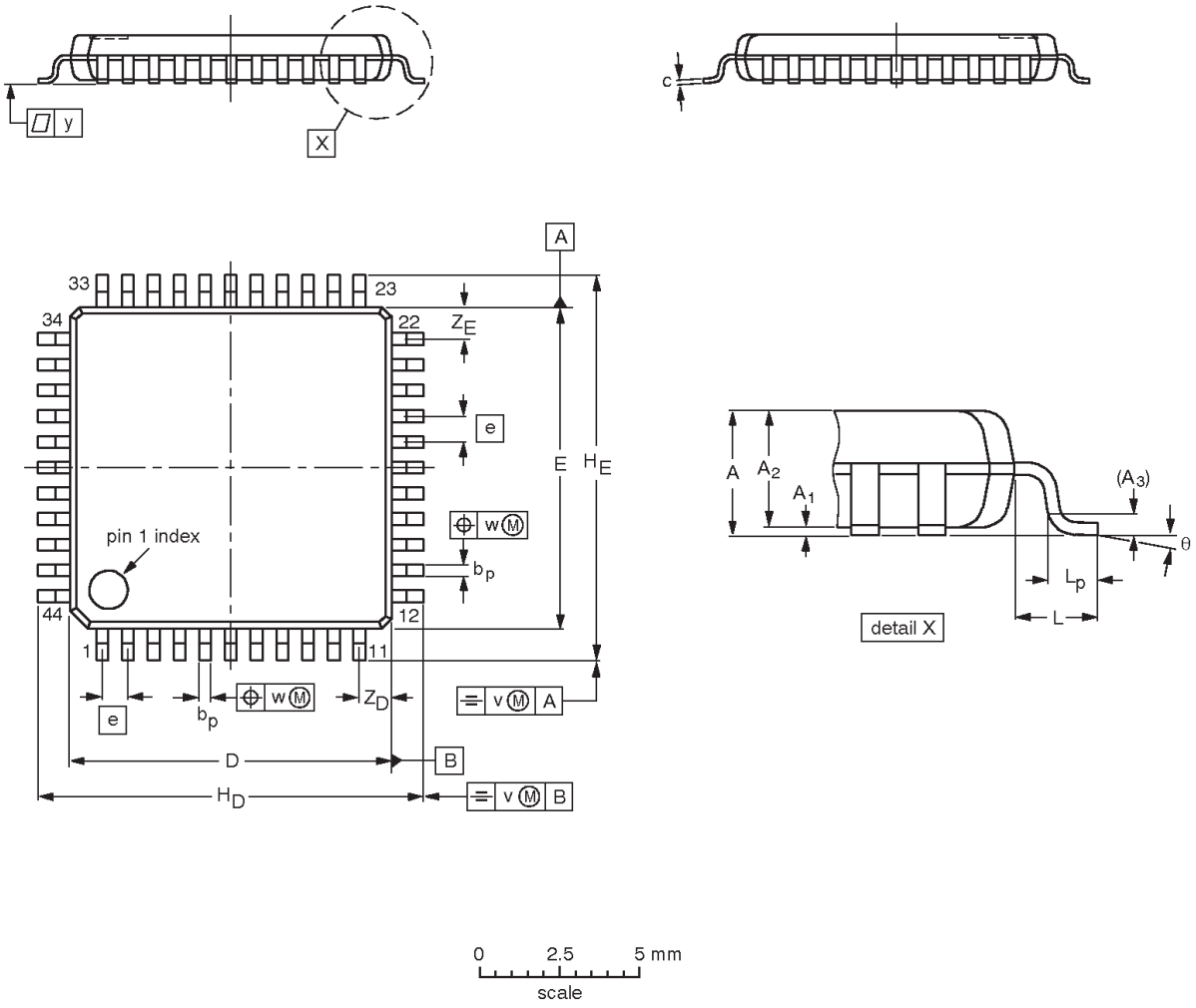
UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	16.66 16.51	16.66 16.51	1.27	16.00 14.99	16.00 14.99	17.65 17.40	17.65 17.40	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.656 0.650	0.656 0.650	0.05	0.63 0.59	0.63 0.59	0.695 0.685	0.695 0.685	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT187-2	112E10	MS-018	EDR-7319			~~99-12-27~~ 01-11-14

LQFP44: plastic low profile quad flat package; 44 leads; body 10 x 10 x 1.4 mm **SOT389-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.45 0.30	0.20 0.12	10.1 9.9	10.1 9.9	0.8	12.15 11.85	12.15 11.85	1	0.75 0.45	0.2	0.2	0.1	1.14 0.85	1.14 0.85	7^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT389-1	136E08	MS-026				~~00-01-19~~ 02-06-07

REVISION HISTORY

Rev	Date	Description
_2	20030911	**Preliminary data (9397 750 11927); ECN 853-2400 30250 of 25 August 2003** Modifications: • Added Watchdog Timer feature • Added DIP40 package
_1	20020723	**Preliminary data (9397 750 10131)**

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